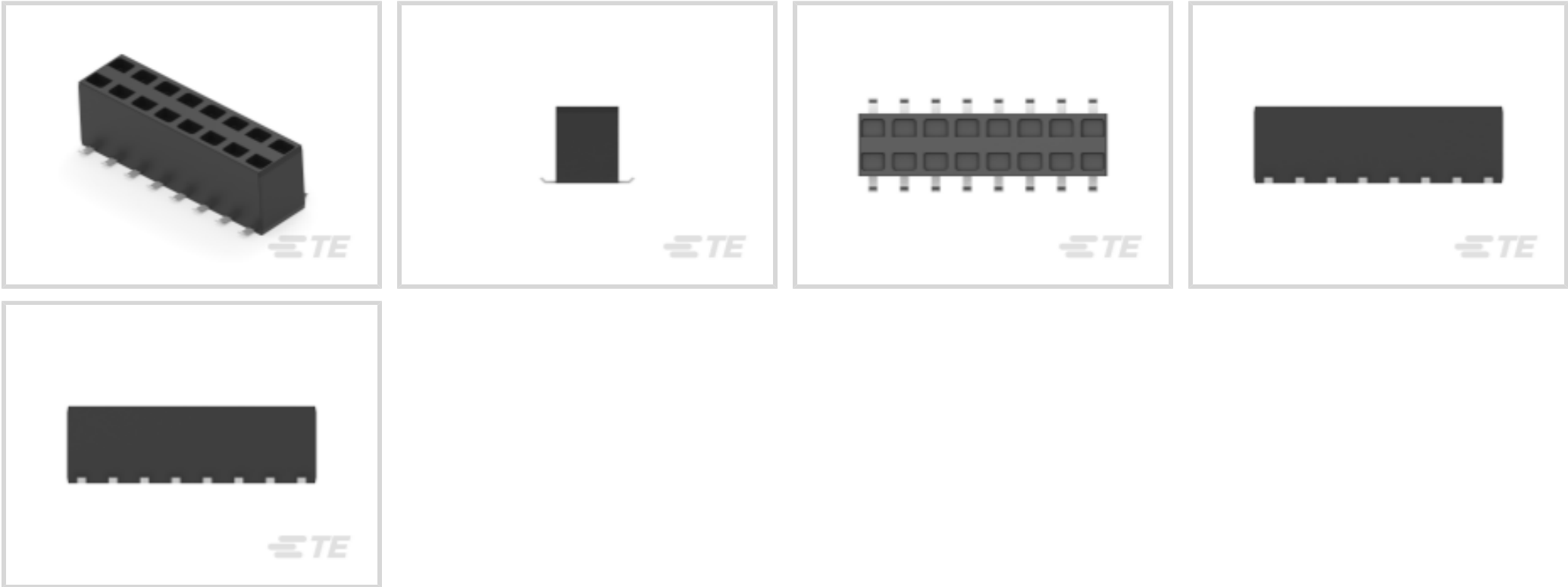




Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Type: **PCB Mount Receptacle**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **16**

Number of Rows: **2**

Features

Product Type Features

PCB Connector Type	PCB Mount Receptacle
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Connector Product Type	Connector Assembly

Configuration Features

Board-to-Board Configuration	Parallel
Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	16
Number of Rows	2

Body Features

Connector Profile	Standard
Primary Product Color	Black



Contact Features

Contact Underplating Material	Nickel
Mating Pin Diameter	.63 mm[.025 in]
Contact Underplating Material Thickness	1.27 μm[50 μin]
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Mating Square Post Dimension	.64 mm[.025 in]
PCB Contact Termination Area Plating Material Thickness	2.5 μm[98.42 μin]
Contact Layout	Inline
Contact Protection Type	Closed Entry Housing
Contact Base Material	Phosphor Bronze
PCB Contact Termination Area Plating Material	Tin
Contact Mating Area Plating Material	Gold (Au)
Contact Type	Socket
Contact Current Rating (Max)	3 A

Termination Features

Rectangular Termination Post & Tail Width	.7 mm[.027 in]
Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
Termination Method to PCB	Surface Mount

Mechanical Attachment

PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Mating Alignment	Without

Housing Features

Mating Entry Location	Bottom & Top
Housing Material	LCP
Centerline (Pitch)	2.54 mm[.1 in]

Dimensions

Row-to-Row Spacing	2.54 mm[.1 in]
Stack Height	9 mm[.354 in]
PCB Thickness (Recommended)	1.6 mm[.063 in]
Connector Height	6.2 mm[.244 in]



Usage Conditions

Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
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Operation/Application

Solder Process Feature	Board Standoff
Circuit Application	Signal

Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Quantity	600
Packaging Method	Reel

Product Compliance

For compliance documentation, visit the product page on [TE.com](#)>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) ‘Guidance on requirements for substances in articles’ posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



TE Part # 826658-8
8P AMPMODU II STIFT LEI



TE Part # 826662-8
8P AMPMODU II STIFT LEI



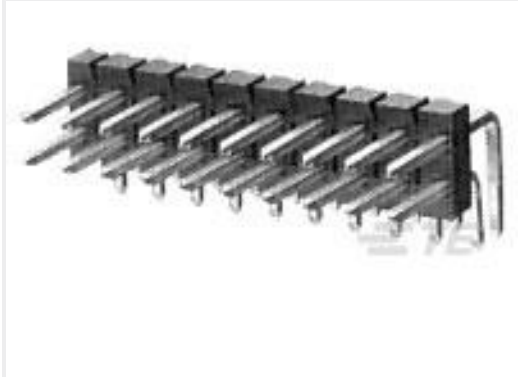
TE Part # 966709-8
2X8P MODU II BREAK AWAY HEADER, SMD



TE Part # 826632-8
8P AMPMODU II PIN HDR.



TE Part # 829394-8
2X8P MOD II UNSHRD HDR, ST, 0.8 AU



TE Part # 826634-8
08P MODU 2 PIN HDR



TE Part # 966269-8
2x8P MOD II BREAK AWAY HDR,SMD, TUBE PKG



TE Part # 1241050-8
2x8P MOD II BREAK AWAY HDR,SMD, BLISTER

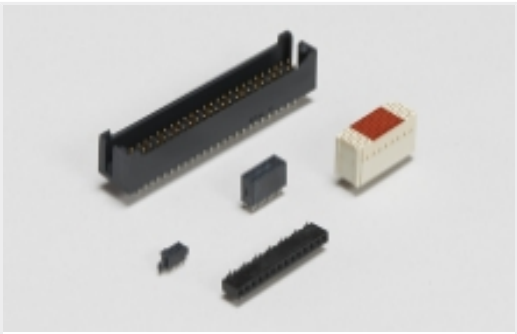


TE Part # 826664-8
8P MOD2 STIFT LEI

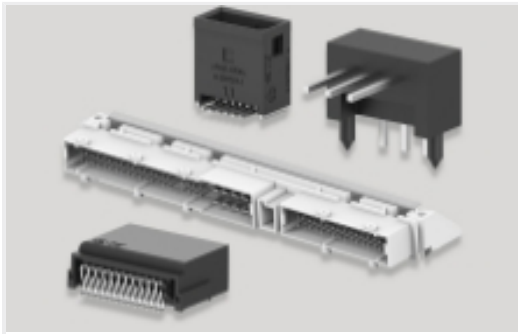


TE Part # 826656-8
8P AMPMODU II STIFT LEI

Also in the Series | [AMPMODU HV-100/HV-190](#)



Board-to-Board Headers & Receptacles(321)



PCB Headers & Receptacles(321)

Customers Also Bought



TE Part #534183-E
SMCQ 16 M AB VV 8-13 CL * H007 137 E005



TE Part #104450-3
04 MTE HDR SRST LATCH W/HLDWN



TE Part #1838275-3
M12 Fld Ser CONN. Male Pin Slidr



TE Part #8-338069-2
MICRO-MATCH SMD FTE

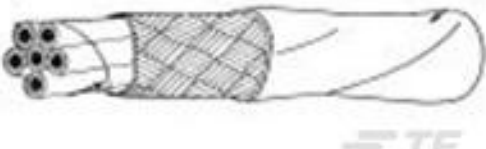




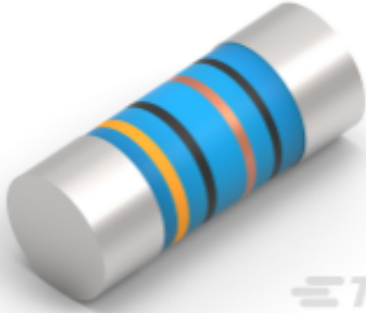
TE Part #3-1393240-3
[RT33L012](#)



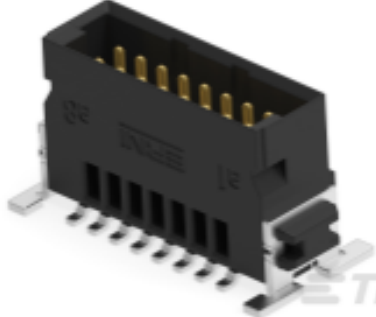
TE Part #2-2176156-1
[TLM 1206 0.5W R020 1% 50PPM 5K RL](#)



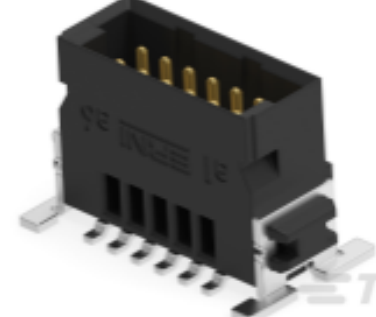
TE Part #6641593001
[55A1161-24-0/2/4/5/6/9-9](#)



TE Part #7-2176315-7
[MELF SMA-A 15R 1% 50PPM 0204 0.4 W](#)



TE Part #474321-E
[SMCQ 16 M AB VV 8-03 CL * H007 137 E005](#)



TE Part #474320-E
[SMCQ 12 M AB VV 8-03 CL * H007 137 E005](#)

Documents

Product Drawings

[2x8P HV100 REC. CON, SMD, GOLD, BLISTER](#)

English

CAD Files

Customer View Model

[ENG_CVM_CVM_969973-8_E.2d_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_969973-8_E.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_969973-8_E.3d_stp.zip](#)

English

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